

Appl. No. : 09/844,959
Filed : 04/27/2001

REMARKS

Claims 11-15 are pending in this application. Claims 11-14 have been amended. New Claim 15 has been added. Support for the amendments and new claim is found in the specification and claims as filed.

Interview

Applicants thank Examiner Vikki H. Trinh for the courteous and helpful interview conducted with Applicants' representatives, Drew S. Hamilton and Gregory A. Hermanson, on October 28, 2005.

Claim Rejection 35 U.S.C. § 103(a)

Claims 11-14 have been rejected under 35 U.S.C. § 103(a) as unpatentable over U.S. 6,066,577 to Cooney, III et al., in view of U.S. 4,187,331 to Ma. To articulate a *prima facie* case of obviousness under 35 U.S.C. § 103(a), the PTO must, *inter alia*, cite prior art that teaches or suggests all the claimed limitations. *In re Royka*, 490 F.3d 982 (C.C.P.A. 1974). Cooney and Ma, alone or in combination, fail to teach or suggest all of the limitations of Claim 11 as amended, which recites an integrated circuit comprising, *inter alia*, "a first layer comprising an organic polymer film, and a second layer which prevents etching of at least a portion of said first layer, said second layer comprising a patterned fluorinated organic polymer."

Cooney discloses an integrated circuit, including a fluorine-free barrier layer 28 deposited on a fluorine rich insulating layer 22, prepared by fluorine doping of a convention silicon dioxide or amorphous carbon layer. Neither the fluorine rich insulating layer 22 nor the fluorine-free barrier 28 prevents etching of the lower layer. Ma discloses an organic polymer resist layer formed on a substrate that is then placed in a low pressure, fluorine-containing atmosphere so as to harden the exposed surface of the layer before heating. The hardened portion of the organic polymer resist merely prevents the deformation of the resist layer during high temperature baking and can be stripped away during etching, and thus does not prevent etching of the substrate below.

Since neither Cooney nor Ma discloses "a first layer comprising an organic polymer film, and a second layer which prevents etching of at least a portion of said first layer, said second layer comprising a patterned fluorinated organic polymer," a *prima facie* case of obviousness

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against Claim 11 and its dependent Claims 12-15 cannot be established. Accordingly, Applicants respectfully request withdrawal of the rejection.

Conclusion


In view of the foregoing amendments and remarks, it is respectfully submitted that the present application is in a condition for allowance. Should the Examiner have any remaining concerns that might prevent the prompt allowance of the application, the Examiner is respectfully invited to contact the undersigned at the telephone number below.

Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: 11/8/05

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AMEND

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